5/3/6

Express Mail Label No. EV826621508US

Docket No.: **PHO-0014**

05-10-2006

103235030

FORM PTO-1595 (Modified)
(Rev. 03-01)
OMB No. 0651-0027 (exp.5/31/2002)
P08A/REV03

ET

U.S. DEPARTMENT OF COMMERCE
Patent and Trademark Office

Tab settings ➔ ➔ ➔ ▼ ▼ ▼ ▼ ▼

To the Director of the United States Pa. ..ademark Office: Please record the attached original documents or copy thereof.

113009 U.S. PTO
11/417026
050306

1. Name of conveying party(ies):
Hyeon Jin SHIN, Young Su CHUNG, Hyun Dam JEONG, Sang Heon HYUN and Nong Baek SEON

Additional names(s) of conveying party(ies) ☐ Yes ☒ No

2. Name and address of receiving party(ies):

Name: **Samsung Corning Co. Ltd.**

Address: **472, Sin-Dong, Yeongtong-Gu**

City: **Suwon-si** State/Prov.: **Gyeonggi-do**

Country: **Republic of Korea** ZIP: **443-732**

Additional name(s) & address(es) ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment ☐ Merger

☐ Security Agreement ☐ Change of Name

☐ Other

Execution Date: **4-9-2006**

4. Application number(s) or patent numbers(s):

If this document is being filed together with a new application, the execution date of the application is: **4-9-2006**

Patent Application No. Filing date

B. Patent No.(s)

05/09/2006 DBYRNE 00000262 061130 11417026
01 FC:8021 40.00 DA

Additional numbers ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: **David E. Rodrigues**

Registration No. **50,604**

Address: **Cantor Colburn LLP**

55 Griffin Road South

City: **Bloomfield** State/Prov.: **CT**

Country: **USA** ZIP: **06002**

6. Total number of applications and patents involved: **1**

7. Total fee (37 CFR 3.41):..................$ **40.00**

☐ Enclosed - Any excess or insufficiency should be credited or debited to deposit account

☒ Authorized to be charged to deposit account

8. Deposit account number:

06-1130

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

David E. Rodrigues — **May 3, 2006**

Name of Person Signing — Signature — Date

Total number of pages including cover sheet, attachments, and document: **3**

Mail documents to be recorded with required cover sheet information to:
Mail Stop Assignment Recordation Services
Director of the United States Patent and Trademark Office
P.O. Box 1450, Alexandria, VA 22313-1450

ASSIGNMENT

WHEREAS We, **Hyeon Jin SHIN of 524/1801, Jinro Apartment, Jungja-3Dong, Jangan-Gu, Suwon-Si, Gyeonggi-Do, 440-300 Republic of Korea** and **Young Su CHUNG of 665/304, 6Danji Apartment, Yeongtong-Dong, Yeongtong-Gu, Suwon-Si, Gyeonggi-Do, 443-733 Republic of Korea** and **Hyun Dam JEONG of 201/206, Dongsuwon LG Village 2Cha, Mangpo-Dong, Yeongtong-Gu, Suwon-Si, Gyeonggi-Do, 443-769 Republic of Korea** and **Sang Heon HYUN of 436/1901, 4Danji Samsung Raemian Apartment, Yeongtong-Dong, Yeongtong-Gu, Suwon-Si, Gyeonggi-Do, 443-738 Republic of Korea** and **Jong Baek SEON of #303, Yangjae-Dong 17-10, Seocho-Gu, Seoul, 137-130 Republic of Korea** (hereinafter referred to as "ASSIGNORS"); have invented certain new and useful improvements in:

SEMICONDUCTOR THIN FILM USING SELF-ASSEMBLED MONOLAYERS AND METHODS OF PRODUCTION THEREOF

which claims priority to Korean Application No. 2005-111745, filed on November 22, 2005, and for which We are about to file an application for Letters Patent of the United States;

AND WHEREAS, Samsung Corning Co., Ltd. (hereinafter referred to as "ASSIGNEE"), a corporation organized and existing under the laws of the Country of Korea, having a place of business at 472, Sin-Dong, Yeongtong-Gu, Suwon-Si, Gyeonggi-Do, 443-732 Republic of Korea, is desirous of acquiring an interest in the United States and all foreign countries, in and to the said invention and Letters Patent to be obtained therefor;

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that, for good and valuable consideration, the receipt of which is hereby acknowledged, We, the said ASSIGNORS have assigned and transferred, and hereby assign and transfer unto the said ASSIGNEE, the entire right, title and interest in and to said invention in the United States and in all foreign countries, including priority rights, as fully set forth and described in said application; and We do hereby authorize and request the Commissioner of Patents to issue said Letters Patent on said application, and any and all Letters Patent that may be issued upon any and all revivals, refilings, continuations, continuations-in-part, divisions and reissues thereof, to the said ASSIGNEE, an assignee of the entire right, title and interest in and to the same, for the sole use and behoof of ASSIGNEE, its successors and assigns; and We do hereby agree that the said ASSIGNEE, may apply for foreign Letters Patent on said invention and that We will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by the said ASSIGNEE, its successors or assigns, and that We will, at the cost and expense of the said ASSIGNEE fully assist and cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date: April 9, 2006 jin L.S.
Hyeon Jin SHIN

Date: April 9, 2006 L.S.
Young Su CHUNG

Date: April 9, 2006 L.S.
Hyun Dam JEONG

Date: April 9, 2006 L.S.
Sang Heon HYUN

Date: April 9, 2006 L.S.
Jong Baek SEON